

Application Serial No.: 10/026,327
Amendment dated: 04/17/2004

Reply to Office action of: 03/10/2004
Attorney Docket No.: RR1731

THE CLAIMS

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in this application:

Listing of Claims:

1 - 7. (Canceled)

8. (Original) A method of forming a slider/suspension assembly for use in a data storage system, comprising:

forming a plurality of adjacently disposed sliders on a wafer, wherein the sliders are positioned in such a manner that trailing edge surfaces of the sliders form a front side of the wafer, and leading edge surfaces of the sliders form a backside of the wafer;

forming a plurality of thin film data transducing elements and a plurality of electrical contact pads on the wafer front side;

metallizing the backside of the wafer so as to metallize the sliders leading edge surfaces while the sliders are on the wafer;

dicing the wafer into a plurality of individual sliders;

positioning a backside of each of a plurality of sliders directly against a corresponding flexure; and

applying a solder fillet bond to a leading edge surface of each of the plurality of sliders, wherein the solder filler flows between a slider leading edge surface and the flexure when heated to form a rigid mechanical connection of

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the slider to the flexure, while enabling the slider to be separated from the flexure on demand.

9. (Original) The method of claim 8, further including forming the flexure of a plurality of overstacked layers.

10. (Original) The method of claim 9, wherein forming the flexure includes forming a metallic bond pad made of a material that is compatible with a fluxless solder process.

11. (Original) The method of claim 10, wherein forming the metallic bond pad includes forming a gold-plated copper layer.

12. (Original) The method of claim 10, wherein forming the flexure further includes forming a second layer and a third layer.

13. (Original) The method of claim 12, wherein forming the second layer of the flexure includes forming a polyimide insulator layer that provides electrical insulation between the first layer and the second layer.

14. (Original) The method of claim 13, wherein forming the third layer of the flexure includes forming a stainless steel flexure tongue that provides resiliency.